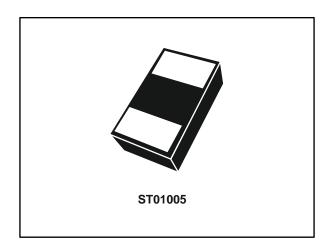


ESDAVLC12-1BV2

Single line bidirectional TVS diode for ESD protection

Datasheet - production data



Features

- 01005 package size
- Ultra small PCB area: 0.08 mm²
- Bidirectional device
- Low capacitance: 7 pF
- Minimum breakdown voltage: V_{BR} = 12 V
- Halogen free and RoHS compliant

Complies with the following standards

- IEC 61000-4-2 level 4
 - 15 kV (air discharge)
 - 8 kV (contact discharge)

Applications

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

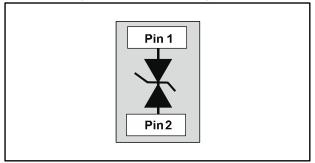
- Tablet PCs, netbooks and notebooks
- Portable multimedia devices and accessories
- Digital cameras and camcorders
- Communication and highly integrated systems
- Smartphones, mobile phone and accessories

Description

The ESDAVLC12-1BV2 is a bidirectional single line TVS diode designed to protect the data lines or other I/O ports against ESD transients.

The device is ideal for applications where both reduced printed circuit board space and high ESD protection levels are required.

Figure 1: Functional diagram



Characteristics ESDAVLC12-1BV2

1 Characteristics

Table 1: Absolute ratings (T_{amb} = 25 °C)

Symbol	Parameter	Value	Unit	
Vpp	Peak pulse voltage	IEC 61000-4-2: Contact discharge Air discharge	8 15	kV
I _{PP}	Peak pulse current 8/20µs		1.5	Α
T _{stg}	Storage junction temperature range	-65 to +150	00	
Tj	Maximum operating junction temperatur	-40 to +125	°C	
TL	Maximum temperature for soldering duri	260	°C	

Figure 2: Electrical characteristics (definitions)

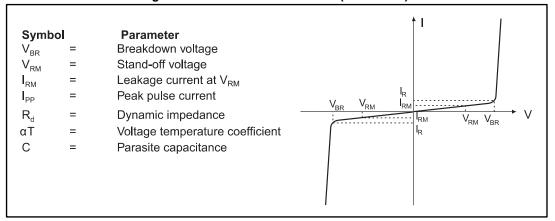
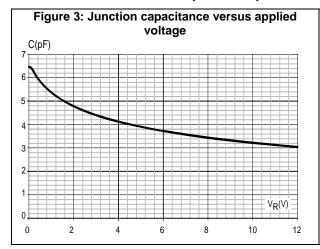


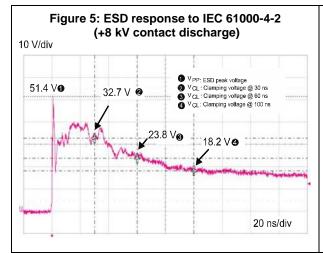
Table 2: Electrical characteristics (T_{amb} = 25 °C)

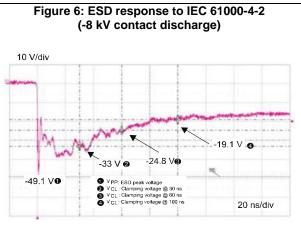
Symbol	Test condition		Тур.	Max.	Unit
V_{BR}	I _R = 1 mA				V
I _{RM}	V _{RM} = 10.5 V		2.5	70	nA
R _d	Dynamic resistance, 100 ns pulse duration			2	Ω
V _{CL}	I _{PP} = 1 A; 8/20 μs			20	V
VcL	8 kV contact discharge after 30 ns IEC 61000-4-2		33		V
Cline	F = 1 MHz, V _R = 0 V		7	10	pF

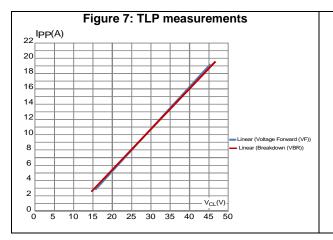
ESDAVLC12-1BV2 Characteristics

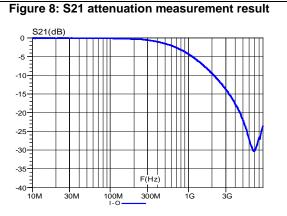
1.1 Characteristics (curves)











2 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

- Epoxy meets UL 94,V0
- Lead-free package

2.1 ST01005 package information

Figure 9: ST01005 package outline

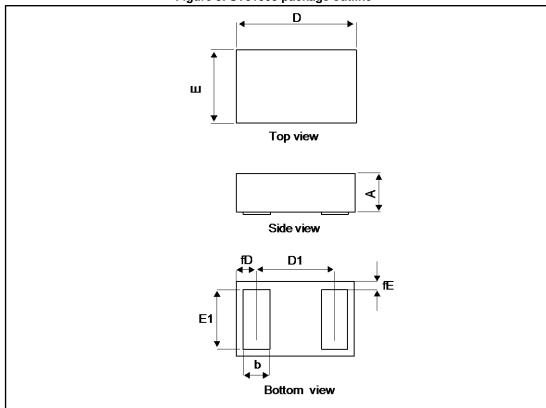


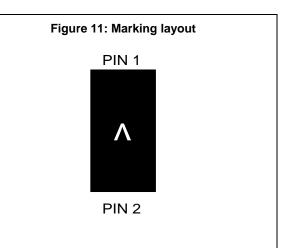
Table 3: ST01005 package mechanical data

	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	0.16	0.18	0.20	0.0063	0.0071	0.0079	
b	0.094	0.104	0.114	0.0037	0.0041	0.0045	
Е	0.17	0.2	0.23	0.0067	0.0078	0.0091	
E1	0.154	0.164	0.174	0.0061	0.0065	0.0069	
D	0.37	0.40	0.43	0.0146	0.0157	0.0169	
D1		0.26	0.6		0.0102	0.0236	
fE	0.010	0.018	0.026	0.0004	0.0007	0.0010	
fD	0.11	0.125	0.13	0.0043	0.0049	0.0051	

Figure 10: Footprint recommendations, dimensions in mm (inches)

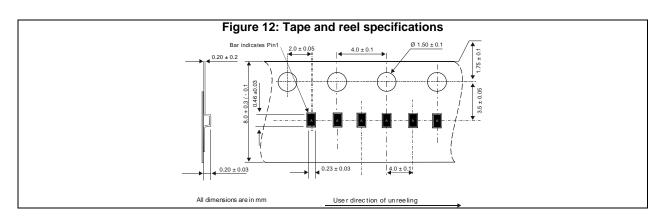
170 µm
120 µm
460 µm

Top side soldermask
Pads





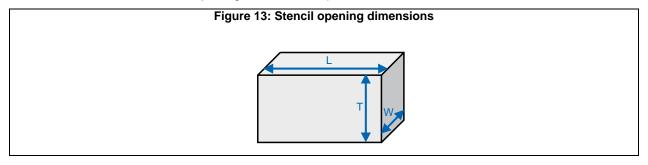
Product marking may be rotated by multiples of 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

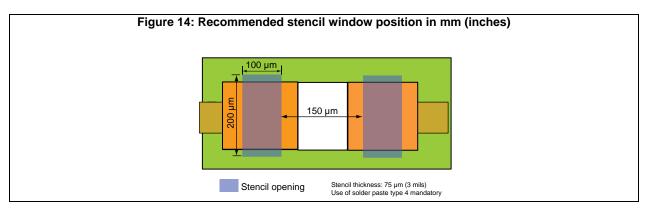


3 Recommendation on PCB assembly

3.1 Stencil opening design

- 1. Reference design
 - a. Stencil opening thickness: 75 µm





3.2 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed.
- 4. Solder paste with fine particles: powder particle size is 20-38 μm.

3.3 **Placement**

- Manual positioning is not recommended.
- It is recommended to use the lead recognition capabilities of the placement system. not the outline centering
- 3. Standard tolerance of ±0.05 mm is recommended.
- 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
- 6. For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

3.4 PCB design preference

- To control the solder paste amount, the closed via is recommended instead of open
- The position of tracks and open vias in the solder area should be well balanced. A symmetrical layout is recommended, to avoid any tilt phenomena caused by asymmetrical solder paste due to solder flow away.

3.5 Reflow profile

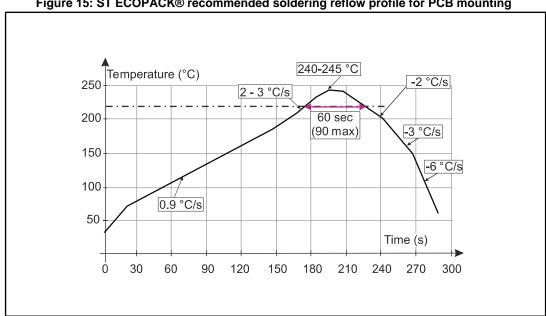


Figure 15: ST ECOPACK® recommended soldering reflow profile for PCB mounting



Minimize air convection currents in the reflow oven to avoid component movement. Maximum soldering profile corresponds to the latest IPC/JEDEC J-STD-020.

Ordering information ESDAVLC12-1BV2

4 Ordering information

Figure 16: Ordering information scheme

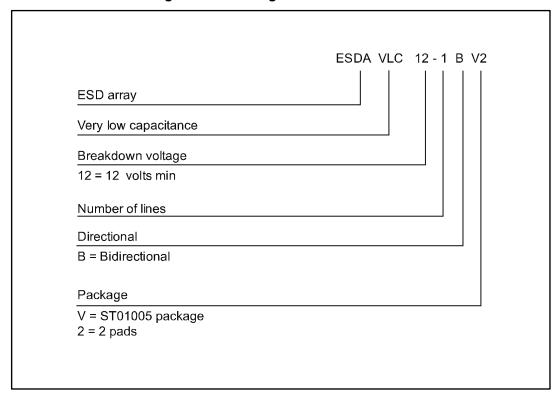


Table 4: Ordering information

Order code		Marking ⁽¹⁾	Package	Weight	Base qty.	Delivery mode
	ESDAVLC12-1BV2	V	ST01005	0.043 mg	20000	Tape and reel

Notes:

5 Revision history

Table 5: Document revision history

Date	Revision	Changes		
02-Dec-2014	1	Initial release.		
23-May-2016	2	Updated Section 9: "Recommendation on PCB assembly" and Section 8.2: "ST01005 package information".		

 $^{^{(1)}}$ The marking can be rotated by multiples of 90° to differentiate assembly location

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ESD119B1W01005E6327XTSA1 ESD5V0L1B02VH6327XTSA1 ESD7451N2T5G 19180-510 CPDT-5V0USP-HF 3.0SMCJ33CA-F
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